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501.39082X00



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): S. UNO, et al

Serial No.: 09/646,671

Filed: September 20, 2000

For: MANUFACTURING METHOD OF SEMICONDUCTOR
INTEGRATED CIRCUIT DEVICE AND SEMICONDUCTOR
INTEGRATED CIRCUIT DEVICE

Group:

Examiner:

PRELIMINARY AMENDMENTCommissioner for Patents
Washington, D.C. 20231

April 5, 2001

Sir:

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

IN THE TITLE OF THE INVENTION:

Please change the title of the invention to:

--METHOD OF MANUFACTURE OF SEMICONDUCTOR INTEGRATED
CIRCUIT DEVICE AND SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE--.

IN THE SPECIFICATION:

Please replace the original specification with the attached Substitute Specification.